


## APPLICATION DATA SHEET

Electronic Version v14

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<b>Title of Invention</b>	CHIP STRUCTURE WITH BUMPS AND A PROCESS FOR FABRICATING THE SAME		
Application Type : regular, utility Attorney Docket Number : 8012-US-PA-1			
Correspondence address: Customer Number: 31561 			
Continuing Data: This is a Division of US application number 10065632, filed 2002-11-05 , now pending.			
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